

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
1	IS&R	2	("6724210").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:02		
2	IS&R	2	("6397361").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 16:56		
3	BRS	3	chip-to-package with connect\$5 with test\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:18		
4	BRS	3	chip-to-package with test\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 16:57		
5	BRS	6	chip-to-package with I/O	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 16:58		
6	BRS	31	chip-to-package and I/O	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 11:57		

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
7	BRS 4		chip-to-package and I/O and transition	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:01		
8	BRS 2		chip-to-package with connection with I/O	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:02		
9	BRS 4		chip-to-package with connection and I/O with semiconductor\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:02		
10	BRS 84		chip-to-package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:21		
11	BRS 2		324/\$.ccls. and chip-to-package and test\$3 with semiconductor\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:05		
12	BRS 4		chip-to-package and test\$3 with semiconductor\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:06		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
13 BRS	337	test\$3 with semiconductor\$1 with i/o	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:08		
14 BRS	26	test\$3 with semiconductor\$1 with i/o with connection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:21		
15 BRS	4	chip-to-package and test\$3 with semiconductor\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:23		
16 BRS	17	chip-to-package and test\$3 with (wafer\$1 or semiconductor\$1 or integrated adj circuit\$1 or Ic\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:24		
17 BRS	8	chip-to-package and test\$3 with (wafer\$1 or semiconductor\$1 or integrated adj circuit\$1 or Ic\$1) and I/O	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/15 17:24		
18 BRS	1	"65556621".PN.	USPAT	2004/06/16 09:05		
19 BRS	1	"6115113".PN.	USPAT	2004/06/16 09:05		
20 BRS	1	"5418820".PN.	USPAT	2004/06/16 09:06		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
21 BRS	8	test\$3 with (semiconductor adj chip) with (semiconductor adj package) with connect\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:27		
22 BRS	43230	test\$3 with semiconductor chip with package with connect\$5 with I/O	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:28		
23 BRS	8	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) with chip with package with connect\$5 with I/O	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:33		
24 BRS	23	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) with chip with package with connect\$5 with (input/output or I/O)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:03		
25 BRS	26	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) with chip\$1 with package\$1 with connect\$5 with (input/output or I/O)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:45		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
		test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) with chip\$1 with package\$1 with connect\$5 with (input/output or I/O) and response with time	USPAT; US-PGPUB; EPO; 2004/06/16 JPO; DERWENT; IBM_TDB			
26 BRS	3	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and chip\$1 with package\$1 with connect\$5 with (input/output or I/O) and response with time	USPAT; US-PGPUB; EPO; 2004/06/16 JPO; DERWENT; IBM_TDB			
27 BRS	8	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and chip\$1 with package\$1 with connect\$5 with (input/output or I/O) and response with time	USPAT; US-PGPUB; EPO; 2004/06/16 JPO; DERWENT; IBM_TDB			
28 BRS	152	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and chip\$1 with package\$1 with connect\$5 with (input/output or I/O)	USPAT; US-PGPUB; EPO; 2004/06/16 JPO; DERWENT; IBM_TDB			
29 BRS	7	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and chip\$1 with package\$1 with connect\$5 with (input/output or I/O) and transition with signal\$1	USPAT; US-PGPUB; EPO; 2004/06/16 JPO; DERWENT; IBM_TDB			

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definitio
30 BRS	7	6397361.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:54		
31 BRS	7	6397361.uref. and (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 09:54		
32 BRS	80	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and I/O with receiver with driver	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:16		
33 BRS	7	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and I/O with receiver with driver and perform\$3 with connect\$5 with (I/O or input/output)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:11		
34 BRS	2	6057698.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:11		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
		test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and I/O with receiver with driver with connect\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 12:05		
35 BRS	36	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and I/O with receiver with driver with connect\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:37		
36 BRS	26	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and I/O with receiver with driver with connect\$5 and respons\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:36		
37 BRS	742	RC adj1 constant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:36		
38 BRS	2	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and I/O with receiver with driver with connect\$5 and RC adj1 constant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:37		
39 BRS	2	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and RC adj1 constant with I/O	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 10:38		

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
40	BRS	27	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and RC adj1 constant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 11:45		
41	IS&R	2	("6058496").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 11:03		
42	IS&R	2	("6348811").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 11:45		
43	BRS	2	chip-to-package with connection with (i/o or input/output)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 11:58		
44	BRS	21	chip-to-package and connection with (i/o or input/output)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 12:05		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
45 BRS	11	test\$3 with (wafer\$1 or IC\$1 or (integrated adj circuit\$1) or semiconductor\$1) and I/O with receiver with driver with connect\$5 and chip\$1 with (package\$1 or die or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 14:39		
46 BRS	207	detect\$3 with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 14:40		
47 BRS	31	detect\$3 with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and compar\$4 with (threshold\$1 or predetermined)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 14:42		
48 BRS	55	detect\$3 with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and (differen\$2 or compar\$4) with (threshold\$1 or predetermined or reference)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 14:42		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
49 BRS	212	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and (differen\$2 or compar\$4) with (threshold\$1 or predetermined or reference)	USPAT; US-PGPUB; EPO; 2004/06/16 JPO; DERWENT; 14:42 IBM_TDB			
50 BRS	162	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and (differen\$2 or compar\$4) with (threshold\$1 or predetermined or reference) and (switch\$3 or latch\$2)	USPAT; US-PGPUB; EPO; 2004/06/16 JPO; DERWENT; 14:43 IBM_TDB			
51 BRS	16	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and (differen\$2 or compar\$4) with (threshold\$1 or predetermined or reference) and (switch\$3 or latch\$2) and fixture	USPAT; US-PGPUB; EPO; 2004/06/16 JPO; DERWENT; 14:44 IBM_TDB			

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
52 BRS	5196	324/713, 763, 765, 538, 711.ccl ls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 14:50		
53 BRS	773	702/117, 118.ccl ls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/16 14:51		
54 BRS	25	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or integrated adj circuit\$1) and (differen\$2 or compar\$4) with (threshold\$1 or predetermined or reference) and (switch\$3 or latch\$2) and package\$1 with chip\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:09		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
55 BRS	4	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and (differen\$2 or compar\$4) with (threshold\$1 or predetermined or reference) and (switch\$3 or latch\$2) and package\$1 with chip\$1 and driver\$1 with receiver\$1	USPAT; US-PGPUB; EPO; 2004/06/16 JPO; DERWENT; IBM_TDB	14:56		
56 BRS	2	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and driver with sensitive with capacitance	USPAT; US-PGPUB; EPO; 2004/06/17 JPO; DERWENT; IBM_TDB	09:11		
57 BRS	5	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and sensitive with capacitance	USPAT; US-PGPUB; EPO; 2004/06/17 JPO; DERWENT; IBM_TDB	09:14		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
58 BRS	5	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and driver with capacitance	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:19		
59 BRS	7	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and weak with driver	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:42		
60 BRS	0	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and driver with deliver\$3 with (current or capacit\$4 or load\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:41		
61 BRS	8	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and weak\$3 with driver\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 09:45		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
62 BRS	31	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and delay with driver\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 10:11		
63 BRS	5	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and delay with driver\$1 with (current\$1 or capacit\$4 or load\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 10:43		
64 BRS	1	"6480817".PN.	USPAT	2004/06/17 10:10		
65 BRS	1	"6292766".PN.	USPAT	2004/06/17 10:10		
66 BRS	0	6662352.uref.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 10:11		
67 BRS	8	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and additional with imped\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 10:48		

Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
68 BRS	37	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and imped\$4 with connection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 10:49		
69 BRS	4	(test\$3 or detect\$3) with connect\$5 with (I/O or input/output) with (semiconductor\$1 or IC\$1 or wafer\$1 or (integrated adj circuit\$1)) and driver with imped\$4 with connection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 10:49		
70 BRS	2	"20020169588"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 12:30		
71 BRS	2	"20020079926"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 12:31		
72 BRS	2	"20020046374"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 12:31		

	Type	Hits	Search Text	DBs	Time Stamp	Comments	Error Definiti on
73	IS&R	2	("5509019").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/17 12:35		